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Media Contact: Mina Galvan
Tel: 408.789.3233
Email: mina.galvan@aosmd.com

Alpha and Omega Semiconductor Adds Two New Advanced MOSFET Package Options for High-Current Applications

The state-of-the-art topside cooling (GTPAK™) and gull-wing (GLPAK™) packages meet increased performance and robust environmental demands

SUNNYVALE, Calif., March 12, 2025 – [Alpha and Omega Semiconductor Limited](#) (AOS) (Nasdaq: AOSL), a designer, developer, and global supplier of a broad range of discrete power devices, wide band gap power devices, power management ICs, and modules, today announced the release of two state-of-the-art surface mounting package options for its industry-leading high power MOSFET portfolio. Designed to meet the robust packaging requirements for the most demanding applications that require increased performance and reliability, the new GTPAK™ and GLPAK™ packages will first be available on AOS' [AOGT66909](#) and [AOGL66901](#) MOSFETs respectively. Combining AOS-proven robust MOSFET technology with advanced packaging know-how, these devices provide low ohmic and high current capabilities, critical to reducing the number of parallel MOSFETs needed in high current designs such as in next-generation e-mobility and industrial applications.

The GTPAK offered with the AOGT66909 is a topside cooling package designed with a large exposed pad for more efficient heat transfer. The topside cooling technology transfers most heat to the heat sink mounted on the top exposed pad. This feature allows the GTPAK to offer a more effective thermal dissipation route than going through the PCB board, allowing a lower-cost PCB, such as FR4, to be used.

The GLPAK offered with the AOGL66901 is a gull-wing version of AOS' successful TOLL package. It is designed using AOS' advanced clip technology to achieve a high inrush current rating. The GLPAK with clip technology offers very low package resistance and parasitic inductance, improving EMI performance compared to other package types that employ standard wire bonding.

The GTPAK and GLPAK packages feature gull-wing leads, enabling excellent solder joint reliability even for insulated metal substrates (IMS) applications. This gull-wing construction also provides enhanced thermal cycling for IMS boards and other critical applications that must meet higher reliability objectives. AOS MOSFETs in the new GTPAK and GLPAK packages are manufactured in IATF16949-certified facilities and are compatible with automated optical inspection (AOI) manufacturing requirements.

"We are committed to delivering new solutions to help our customers meet or exceed their power performance requirements. By offering our industry-leading MOSFETs in the new robust GTPAK and GLPAK packages, AOS allows designers to select from two state-of-the-art packaging technologies that offer significant performance improvements. Furthermore, the advanced technologies in our AOGT66909 and AOGL66901 MOSFETs will help simplify new designs by reducing the number of devices needed while also providing the necessary higher current capability that makes overall system cost savings possible," said Peter H. Wilson, Marketing Sr. Director of MOSFET product line at AOS.

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Technical Highlights

Part Number	Package	V _{DS} (V)	V _{GS} (±V)	T _J (°C)	Continuous Drain Current (A)		Pulsed Drain Current (A)	R _{DS(ON)} Max (mOhms) @10V
					@25°C	@100°C	@25°C	
AOGT66909	GTPAK	100	20	175	366	258	1464	1.5
AOGL66901	GLPAK	100	20	175	448	316	1790	1.25

Pricing and Availability

The AOGT66909 and AOGL66901 MOSFETs are immediately available in production quantities with a lead time of 14-16 weeks. The unit prices in 1,000-piece quantities are \$3.6 and \$3.15, respectively.

About AOS

Alpha and Omega Semiconductor Limited, or [AOS](#), is a designer, developer, and global supplier of a broad range of discrete power devices, wide bandgap power devices, power management ICs, and modules, including a wide portfolio of [Power MOSFET](#), [SiC](#), [IGBT](#), [IPM](#), [TVS](#), [HV Gate Drivers](#), [Power IC](#), and [Digital Power](#) products. AOS has developed extensive intellectual property and technical knowledge that encompasses the latest advancements in the power semiconductor industry, which enables us to introduce innovative products to address the increasingly complex power requirements of advanced electronics. AOS differentiates itself by integrating its Discrete and IC semiconductor process technology, product design, and advanced packaging know-how to develop high-performance power management solutions. AOS' portfolio of products targets high-volume applications, including personal computers, graphics cards, datacenters, AI servers, smartphones, consumer and industrial motor controls, TVs, lightings, automotive electronics, and power supply units for various equipment. For more information, please visit www.aosmd.com.

Forward-Looking Statements

This press release contains forward-looking statements based on current expectations, estimates, forecasts, and projections of future performance based on management's judgment, beliefs, current trends, and anticipated product performance. These forward-looking statements include, without limitation, references to the efficiency and capability of new products and the potential to expand into new markets. Forward-looking statements involve risks and uncertainties that may cause actual results to differ materially from those in forward-looking statements. These factors include but are not limited to, the actual product performance in volume production, the quality and reliability of the product, our ability to achieve design wins, the general business and economic conditions, the state of the semiconductor industry, and other risks as described in the Company's annual report and other filings with the U.S. Securities and Exchange Commission. Although the Company believes that the expectations reflected in the forward-looking statements are reasonable, it cannot guarantee future results, activity level, performance, or achievements. You should not place undue reliance on these forward-looking statements. All information provided in this press release is as of today's date unless otherwise stated, and AOS undertakes no duty to update such information except as required under applicable law.

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